



Anode: 10nm of NiCr -inside bottom surface. See note 2.

Border: 200nm of NiCr followed by 400nm of Cu. See note 3.

Sidewall Seal Surfaces: 200nm of NiCr followed by 400nm of Cu without a vacuum break. See note 4.

- Notes-
- 1. For component details see Drawing Vers3Tile10_19_2016.
 - 2. Anode consists of 10nm of NiCr. Film can come up to sidewall. Sidewall to be masked so that no metalization is on it.
 - 3. Border consists of 200nm of NiCr followed by 400nm of Cu without a vacuum break between depositions. Border is applied on top of the anode layer and should make electrical contact on all 4 sides.
 - 4. The sidewall seal surface consists of 200nm of NiCr followed by 400nm of Cu without a vacuum break between depositions. Sidewall to be masked as in note 2. Metalization to pass Scotch Tape adhesion test.
 - 5. The copper tube can be (gently) bent to avoid interference with fixturing under the tile.
 - 6. UC will provide a temporary SS clamp for stabilizing the copper tubes during deposition if desired.

Copper tube: See note 5.

Temporary SS clamp: see note 6.

DRAWN rnorthrop	10/19/2016	University of Chicago		
CHECKED		TITLE		
QA		Ceramic Tile Base Assembly Electroding Detail		
MFG				
APPROVED		SIZE C	DWG NO CERAMTBAmetal10_19_16	REV
		SCALE	SHEET 1 OF 1	